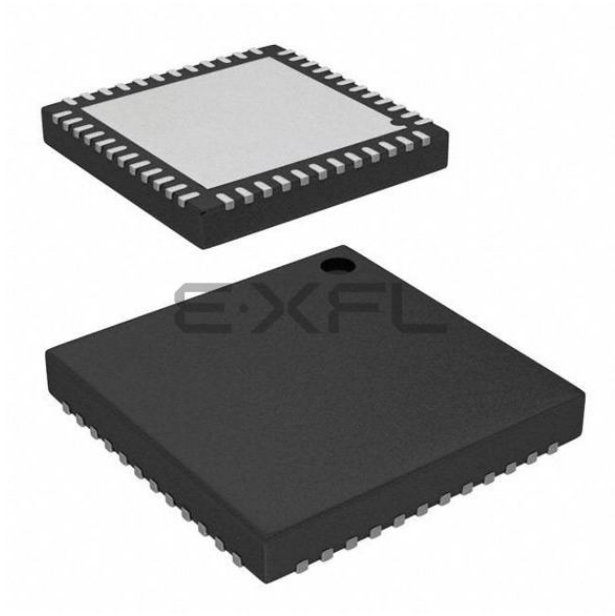

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	M8C
Core Size	8-Bit
Speed	24MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	44
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.25V
Data Converters	A/D 4x14b; D/A 4x9b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	48-QFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c28643-24ltxi

Figure 4. Analog System Block Diagram for CY8C28x43 Devices

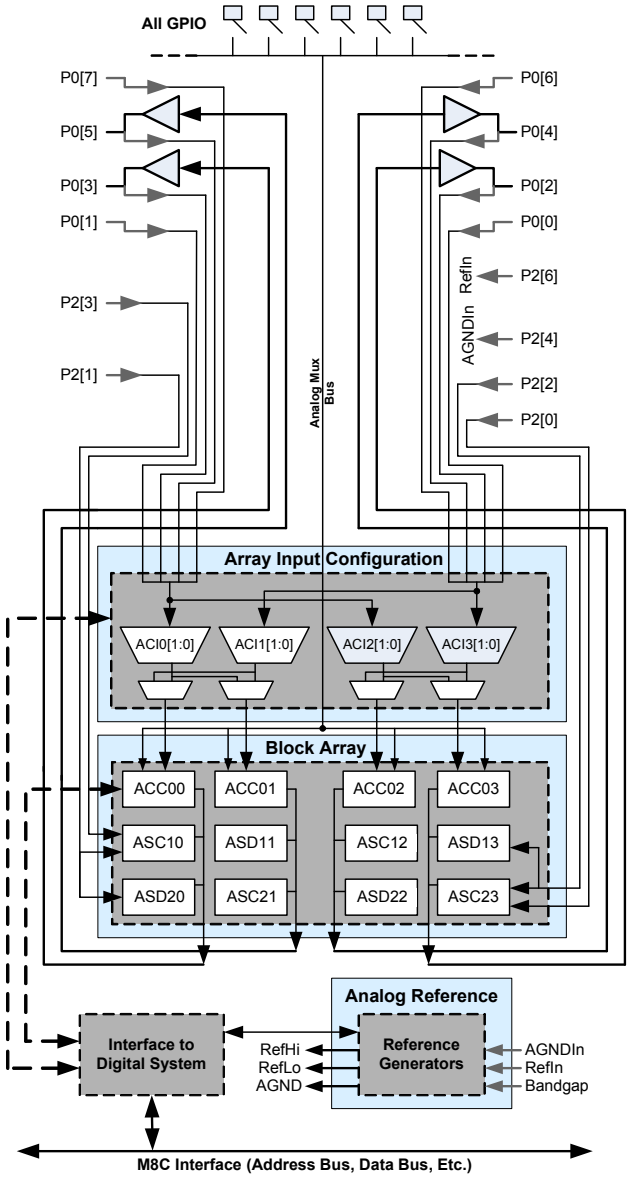
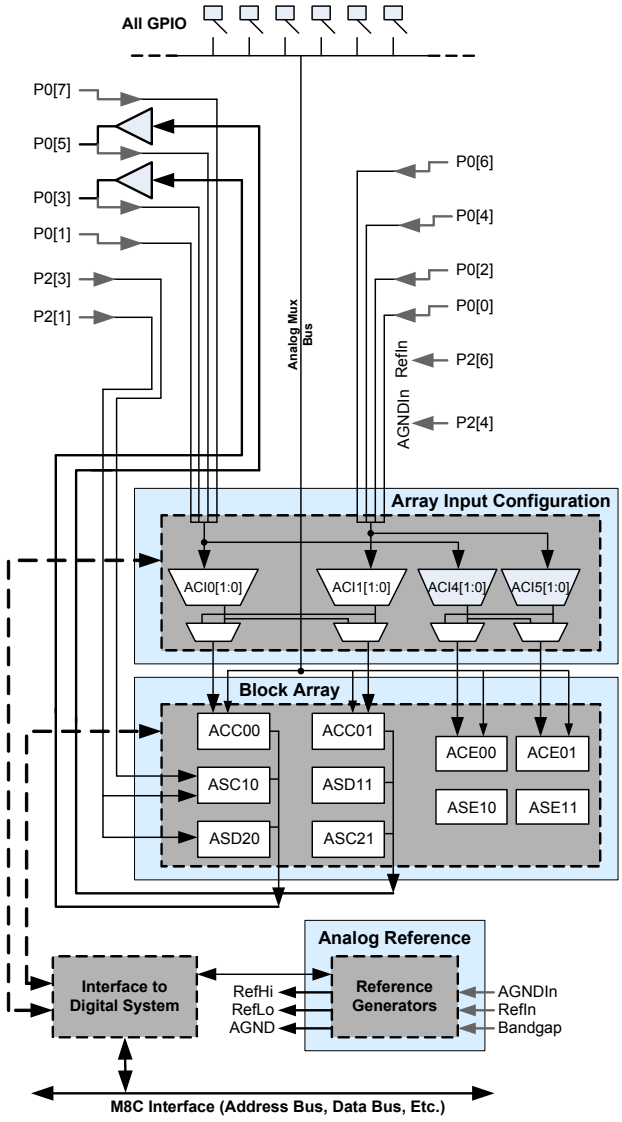


Figure 5. Analog System Block Diagram for CY8C28x33 Devices



Designing with PSoC Designer

The development process for the PSoC device differs from that of a traditional fixed-function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and lowering inventory costs. These configurable resources, called PSoC blocks, have the ability to implement a wide variety of user-selectable functions. The PSoC development process is:

1. Select user modules.
2. Configure user modules.
3. Organize and connect.
4. Generate, verify, and debug.

Select User Modules

PSoC Designer provides a library of prebuilt, pretested hardware peripheral components called “user modules.” User modules make selecting and implementing peripheral devices, both analog and digital, simple.

Configure User Modules

Each user module that you select establishes the basic register settings that implement the selected function. They also provide parameters and properties that allow you to tailor their precise configuration to your particular application. For example, a PWM User Module configures one or more digital PSoC blocks, one for each eight bits of resolution. Using these parameters, you can establish the pulse width and duty cycle. Configure the parameters and properties to correspond to your chosen application. Enter values directly or by selecting values from drop-down menus. All of the user modules are documented in datasheets that may be viewed directly in PSoC Designer or on the Cypress website. These user module datasheets explain the internal operation of the user module and provide performance specifications. Each datasheet describes the use of each user module parameter, and other information that you may need to successfully implement your design.

Organize and Connect

Build signal chains at the chip level by interconnecting user modules to each other and the I/O pins. Perform the selection, configuration, and routing so that you have complete control over all on-chip resources.

Generate, Verify, and Debug

When you are ready to test the hardware configuration or move on to developing code for the project, perform the “Generate Configuration Files” step. This causes PSoC Designer to generate source code that automatically configures the device to your specification and provides the software for the system. The generated code provides APIs with high-level functions to control and respond to hardware events at run time, and interrupt service routines that you can adapt as needed.

A complete code development environment lets you to develop and customize your applications in C, assembly language, or both.

The last step in the development process takes place inside PSoC Designer's Debugger (accessed by clicking the Connect icon). PSoC Designer downloads the HEX image to the ICE where it runs at full-speed. PSoC Designer debugging capabilities rival those of systems costing many times more. In addition to traditional single-step, run-to-breakpoint, and watch-variable features, the debug interface provides a large trace buffer. It lets you to define complex breakpoint events that include monitoring address and data bus values, memory locations, and external signals.

Pinouts

This section describes, lists, and illustrates the CY8C28xxx PSoC device pins and pinout configurations.

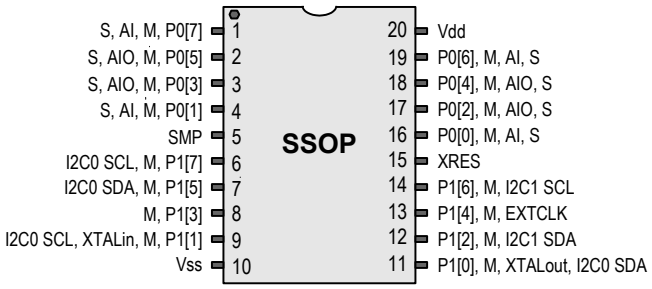
The CY8C28xxx PSoC devices are available in a variety of packages which are listed and illustrated in the following tables. Every port pin (labeled with a “P”) is capable of Digital I/O. However, V_{SS}, V_{DD}, SMP, and XRES are not capable of Digital I/O.

20-pin Part Pinout

Table 3. 20-pin Part Pinout (SSOP)

Pin No.	Type		Pin Name	Description
	Digital	Analog		
1	I/O	I, M, S	P0[7]	Analog column mux and SAR ADC input.[5]
2	I/O	I/O, M, S	P0[5]	Analog column mux and SAR ADC input. Analog column output.[5, 6]
3	I/O	I/O, M, S	P0[3]	Analog column mux and SAR ADC input. Analog column output.[5, 6]
4	I/O	I, M, S	P0[1]	Analog column mux and SAR ADC input.[5]
5	Output		SMP	Switch Mode Pump (SMP) connection to external components.
6	I/O	M	P1[7]	I2C0 Serial Clock (SCL).
7	I/O	M	P1[5]	I2C0 Serial Data (SDA).
8	I/O	M	P1[3]	
9	I/O	M	P1[1]	Crystal Input (XTALin), I2C0 Serial Clock (SCL), ISSP-SCLK[4].
10	Power		V_{SS}	Ground connection.
11	I/O	M	P1[0]	Crystal Output (XTALout), I2C0 Serial Data (SDA), ISSP-SDATA[4].
12	I/O	M	P1[2]	I2C1 Serial Data (SDA).[7]
13	I/O	M	P1[4]	Optional External Clock Input (EXTCLK).
14	I/O	M	P1[6]	I2C1 Serial Clock (SCL).[7]
15	Input		XRES	Active high external reset with internal pull-down.
16	I/O	I, M, S	P0[0]	Analog column mux and SAR ADC input.[5]
17	I/O	I/O, M, S	P0[2]	Analog column mux and SAR ADC input. Analog column output.[5, 8]
18	I/O	I/O, M, S	P0[4]	Analog column mux and SAR ADC input. Analog column output.[5, 8]
19	I/O	I, M, S	P0[6]	Analog column mux and SAR ADC input.[5]
20	Power		V_{DD}	Supply voltage.

CY8C28243 20-pin PSoC Device



LEGEND: A = Analog, I = Input, O = Output, S = SAR ADC Input, and M = Analog Mux Bus Input.

Notes
4. These are the ISSP pins, which are not High Z at POR (Power On Reset). See the *PSoC Technical Reference Manual* for CY8C28xxx PSoC devices for details.
5. CY8C28x52 and CY8C28x23 devices do not have a SAR ADC. Therefore, this pin does not function as a SAR ADC input for these devices.
6. CY8C28x13 and CY8C28x03 devices do not have any analog output buffers. Therefore, this pin does not function as an analog column output for these devices.
7. CY8C28x52, CY8C28x13, and CY8C28x33 devices only have one I2C block. Therefore, this GPIO does not function as an I2C pin for these devices.
8. CY8C28x33, CY8C28x23, CY8C28x13, and CY8C28x03 devices do not have an analog output buffer for this pin. Therefore, this pin does not function as an analog column output for these devices.

Register Reference

This section lists the registers of the CY8C28xxx PSoC devices. For detailed register information, reference the *PSoC Technical Reference Manual* for CY8C28xxx PSoC devices.

Register Conventions

The register conventions specific to this section are listed in the following table.

Convention	Description
R	Read register or bit(s)
W	Write register or bit(s)
L	Logical register or bit(s)
C	Clearable register or bit(s)
#	Access is bit specific

Register Mapping Tables

CY8C28xxx PSoC devices have a total register address space of 512 bytes. The register space is referred to as I/O space and is divided into two banks. The XIO bit in the Flag register (CPU_F) determines which bank of registers CPU instructions access. When the XIO bit is set the registers in Bank 1 are accessed by CPU instructions. When the XIO bit is cleared the registers in Bank 0 are accessed by CPU instructions.

Note In the following register mapping tables, blank fields are reserved and should not be accessed.

Table 11. CY8C28x13 Register Map Bank 1 Table: Configuration Space

Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access
PRT0DM0	00	RW	DBC20FN	40	RW		80		RDI2RI	C0	RW
PRT0DM1	01	RW	DBC20IN	41	RW	SADC_TSCMPL	81	RW	RDI2SYN	C1	RW
PRT0IC0	02	RW	DBC20OU	42	RW	SADC_TSCMPH	82	RW	RDI2IS	C2	RW
PRT0IC1	03	RW	DBC20CR1	43	RW	ACE_AMD_CR1	83	RW	RDI2LT0	C3	RW
PRT1DM0	04	RW	DBC21FN	44	RW		84		RDI2LT1	C4	RW
PRT1DM1	05	RW	DBC21IN	45	RW	ACE_PWM_CR	85	RW	RDI2RO0	C5	RW
PRT1IC0	06	RW	DBC21OU	46	RW	ACE_ADC0_CR	86	RW	RDI2RO1	C6	RW
PRT1IC1	07	RW	DBC21CR1	47	RW	ACE_ADC1_CR	87	RW	RDI2DSM	C7	RW
PRT2DM0	08	RW	DCC22FN	48	RW		88			C8	
PRT2DM1	09	RW	DCC22IN	49	RW	ACE_CLK_CR0	89	RW		C9	
PRT2IC0	0A	RW	DCC22OU	4A	RW	ACE_CLK_CR1	8A	RW		CA	
PRT2IC1	0B	RW	DCC22CR1	4B	RW	ACE_CLK_CR3	8B	RW		CB	
PRT3DM0	0C	RW	DCC23FN	4C	RW		8C	RW		CC	
PRT3DM1	0D	RW	DCC23IN	4D	RW	ACE01CR1	8D	RW		CD	
PRT3IC0	0E	RW	DCC23OU	4E	RW	ACE01CR2	8E	RW		CE	
PRT3IC1	0F	RW	DCC23CR1	4F	RW	ASE11CR0	8F	RW		CF	
PRT4DM0	10	RW		50			90		GDI_O_IN	D0	RW
PRT4DM1	11	RW		51		DEC0_CR0	91	RW	GDI_E_IN	D1	RW
PRT4IC0	12	RW		52		DEC_CR3	92	RW	GDI_O_OU	D2	RW
PRT4IC1	13	RW		53			93		GDI_E_OU	D3	RW
PRT5DM0	14	RW		54			94		DEC0_CR	D4	RW
PRT5DM1	15	RW		55		DEC1_CR0	95	RW	DEC1_CR	D5	RW
PRT5IC0	16	RW		56			96			D6	
PRT5IC1	17	RW		57			97			D7	
	18			58			98		MUX_CR0	D8	RW
	19			59			99		MUX_CR1	D9	RW
	1A			5A		DEC_CR5	9A	RW	MUX_CR2	DA	RW
	1B			5B			9B		MUX_CR3	DB	RW
	1C			5C			9C		IDAC_CR1	DC	RW
	1D			5D			9D		OSC_GO_EN	DD	RW
	1E			5E			9E		OSC_CR4	DE	RW
	1F			5F			9F		OSC_CR3	DF	RW
DBC00FN	20	RW		60		GDI_O_IN_CR	A0	RW	OSC_CR0	E0	RW
DBC00IN	21	RW		61		GDI_E_IN_CR	A1	RW	OSC_CR1	E1	RW
DBC00OU	22	RW		62		GDI_O_OU_CR	A2	RW	OSC_CR2	E2	RW
DBC00CR1	23	RW		63		GDI_E_OU_CR	A3	RW	VLT_CR	E3	RW
DBC01FN	24	RW		64		RTC_H	A4	RW	VLT_CMP	E4	RW
DBC01IN	25	RW		65		RTC_M	A5	RW	ADC0_TR	E5	RW
DBC01OU	26	RW		66		RTC_S	A6	RW	ADC1_TR	E6	RW
DBC01CR1	27	RW		67		RTC_CR	A7	RW	IDAC_CR2	E7	RW
DCC02FN	28	RW		68		SADC_CR0	A8	RW	IMO_TR	E8	RW
DCC02IN	29	RW		69		SADC_CR1	A9	RW	ILO_TR	E9	RW
DCC02OU	2A	RW	AMUX_CFG1	6A	RW	SADC_CR2	AA	RW	BDG_TR	EA	RW
DCC02CR1	2B	RW		6B		SADC_CR3	AB	RW	ECO_TR	EB	RW
DCC03FN	2C	RW	TMP_DR0	6C	RW	SADC_CR4	AC	RW	MUX_CR4	EC	RW
DCC03IN	2D	RW	TMP_DR1	6D	RW	I2C0_ADDR	AD	RW	MUX_CR5	ED	RW
DCC03OU	2E	RW	TMP_DR2	6E	RW		AE			EE	
DCC03CR1	2F	RW	TMP_DR3	6F	RW	AMUX_CLK	AF	RW		EF	
DBC10FN	30	RW		70		RDI0RI	B0	RW		F0	
DBC10IN	31	RW	SADC_TSCR0	71	RW	RDI0SYN	B1	RW		F1	
DBC10OU	32	RW	SADC_TSCR1	72	RW	RDI0IS	B2	RW		F2	
DBC10CR1	33	RW	ACE_AMD_CR0	73	RW	RDI0LT0	B3	RW		F3	
DBC11FN	34	RW		74	RW	RDI0LT1	B4	RW		F4	
DBC11IN	35	RW	ACE_AMX_IN	75	RW	RDI0RO0	B5	RW		F5	
DBC11OU	36	RW	ACE_CMP_CR0	76	RW	RDI0RO1	B6	RW		F6	
DBC11CR1	37	RW	ACE_CMP_CR1	77	RW	RDIODSM	B7	RW	CPU_F	F7	RL
DCC12FN	38	RW		78		RDI1RI	B8	RW		F8	
DCC12IN	39	RW	ACE_CMP_GI_EN	79	RW	RDI1SYN	B9	RW		F9	
DCC12OU	3A	RW	ACE_ALT_CR0	7A	RW	RDI1IS	BA	RW	FLS_PR1	FA	RW
DCC12CR1	3B	RW	ACE_ABF_CR0	7B	RW	RDI1LT0	BB	RW		FB	
DCC13FN	3C	RW		7C		RDI1LT1	BC	RW		FC	
DCC13IN	3D	RW	ACE0_CR1	7D	RW	RDI1RO0	BD	RW	IDAC_CR0	FD	RW
DCC13OU	3E	RW	ACE0_CR2	7E	RW	RDI1RO1	BE	RW	CPU_SCR1	FE	#
DCC13CR1	3F	RW	ACE0_CR3	7F	RW	RDI1DSM	BF	RW	CPU_SCR0	FF	#

Blank fields are Reserved and should not be accessed. # Access is bit specific. *Address has a dual purpose, see “Mapping Exceptions” on page 251

Table 13. CY8C28x23 Register Map Bank 1 Table: Configuration Space

Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access
PRT0DM0	00	RW	DBC20FN	40	RW		80		RDI2RI	C0	RW
PRT0DM1	01	RW	DBC20IN	41	RW		81		RDI2SYN	C1	RW
PRT0IC0	02	RW	DBC20OU	42	RW		82		RDI2IS	C2	RW
PRT0IC1	03	RW	DBC20CR1	43	RW		83		RDI2LT0	C3	RW
PRT1DM0	04	RW	DBC21FN	44	RW		84		RDI2LT1	C4	RW
PRT1DM1	05	RW	DBC21IN	45	RW		85		RDI2RO0	C5	RW
PRT1IC0	06	RW	DBC21OU	46	RW		86		RDI2RO1	C6	RW
PRT1IC1	07	RW	DBC21CR1	47	RW		87		RDI2DSM	C7	RW
PRT2DM0	08	RW	DCC22FN	48	RW		88			C8	
PRT2DM1	09	RW	DCC22IN	49	RW		89			C9	
PRT2IC0	0A	RW	DCC22OU	4A	RW		8A			CA	
PRT2IC1	0B	RW	DCC22CR1	4B	RW		8B			CB	
PRT3DM0	0C	RW	DCC23FN	4C	RW		8C			CC	
PRT3DM1	0D	RW	DCC23IN	4D	RW		8D			CD	
PRT3IC0	0E	RW	DCC23OU	4E	RW		8E			CE	
PRT3IC1	0F	RW	DCC23CR1	4F	RW		8F			CF	
PRT4DM0	10	RW		50			90		GDI_O_IN	D0	RW
PRT4DM1	11	RW		51		DEC0_CR0	91	RW	GDI_E_IN	D1	RW
PRT4IC0	12	RW		52		DEC_CR3	92	RW	GDI_O_OU	D2	RW
PRT4IC1	13	RW		53			93	RW	GDI_E_OU	D3	RW
PRT5DM0	14	RW		54			94	RW	DEC0_CR	D4	RW
PRT5DM1	15	RW		55		DEC1_CR0	95	RW	DEC1_CR	D5	RW
PRT5IC0	16	RW		56			96			D6	
PRT5IC1	17	RW		57			97			D7	
	18			58			98			D8	
	19			59			99			D9	
	1A			5A		DEC_CR5	9A	RW		DA	
	1B			5B			9B			DB	
	1C			5C			9C			DC	
	1D			5D			9D		OSC_GO_EN	DD	RW
	1E			5E			9E		OSC_CR4	DE	RW
	1F			5F			9F		OSC_CR3	DF	RW
DBC00FN	20	RW	CLK_CR0	60	RW	GDI_O_IN_CR	A0	RW	OSC_CR0	E0	RW
DBC00IN	21	RW	CLK_CR1	61	RW	GDI_E_IN_CR	A1	RW	OSC_CR1	E1	RW
DBC00OU	22	RW	ABF_CR0	62	RW	GDI_O_OU_CR	A2	RW	OSC_CR2	E2	RW
DBC00CR1	23	RW	AMD_CR0	63	RW	GDI_E_OU_CR	A3	RW	VLT_CR	E3	RW
DBC01FN	24	RW	CMP_GO_EN	64	RW	RTC_H	A4	RW	VLT_CMP	E4	RW
DBC01IN	25	RW		65		RTC_M	A5	RW		E5	
DBC01OU	26	RW	AMD_CR1	66	RW	RTC_S	A6	RW		E6	
DBC01CR1	27	RW	ALT_CR0	67	RW	RTC_CR	A7	RW		E7	
DCC02FN	28	RW		68			A8		IMO_TR	E8	RW
DCC02IN	29	RW	CLK_CR2	69	RW		A9		ILO_TR	E9	RW
DCC02OU	2A	RW		6A			AA		BDG_TR	EA	RW
DCC02CR1	2B	RW	I2C1_CFG	6B	RW		AB		ECO_TR	EB	RW
DCC03FN	2C	RW	TMP_DR0	6C	RW		AC			EC	
DCC03IN	2D	RW	TMP_DR1	6D	RW	I2C0_ADDR	AD	RW		ED	
DCC03OU	2E	RW	TMP_DR2	6E	RW	I2C1_ADDR	AE	RW		EE	
DCC03CR1	2F	RW	TMP_DR3	6F	RW	AMUX_CLK	AF	RW		EF	
DBC10FN	30	RW		70		RDI0RI	B0	RW		F0	
DBC10IN	31	RW		71		RDI0SYN	B1	RW		F1	
DBC10OU	32	RW		72		RDI0IS	B2	RW		F2	
DBC10CR1	33	RW		73		RDI0LT0	B3	RW		F3	
DBC11FN	34	RW		74		RDI0LT1	B4	RW		F4	
DBC11IN	35	RW		75		RDI0RO0	B5	RW		F5	
DBC11OU	36	RW		76		RDI0RO1	B6	RW		F6	
DBC11CR1	37	RW		77		RDIODSM	B7	RW	CPU_F	F7	RL
DCC12FN	38	RW		78		RDI1RI	B8	RW		F8	
DCC12IN	39	RW		79		RDI1SYN	B9	RW		F9	
DCC12OU	3A	RW		7A		RDI1IS	BA	RW	FLS_PR1	FA	RW
DCC12CR1	3B	RW		7B		RDI1LT0	BB	RW		FB	
DCC13FN	3C	RW		7C		RDI1LT1	BC	RW		FC	
DCC13IN	3D	RW		7D		RDI1RO0	BD	RW		FD	
DCC13OU	3E	RW		7E		RDI1RO1	BE	RW	CPU_SCR1	FE	#
DCC13CR1	3F	RW		7F		RDI1DSM	BF	RW	CPU_SCR0	FF	#

Blank fields are Reserved and should not be accessed. # Access is bit specific. *Address has a dual purpose, see “Mapping Exceptions” on page 251

Table 14. CY8C28x33 Register Map Bank 0 Table: User Space

Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access
PRT0DR	00	RW	DBC20DR0	40	#	ASC10CR0	80	RW	RDI2RI	C0	RW
PRT0IE	01	RW	DBC20DR1	41	W	ASC10CR1	81	RW	RDI2SYN	C1	RW
PRT0GS	02	RW	DBC20DR2	42	RW	ASC10CR2	82	RW	RDI2IS	C2	RW
PRT0DM2	03	RW	DBC20CR0	43	#	ASC10CR3	83	RW	RDI2LT0	C3	RW
PRT1DR	04	RW	DBC21DR0	44	#	ASD11CR0	84	RW	RDI2LT1	C4	RW
PRT1IE	05	RW	DBC21DR1	45	W	ASD11CR1	85	RW	RDI2RO0	C5	RW
PRT1GS	06	RW	DBC21DR2	46	RW	ASD11CR2	86	RW	RDI2RO1	C6	RW
PRT1DM2	07	RW	DBC21CR0	47	#	ASD11CR3	87	RW	RDI2DSM	C7	RW
PRT2DR	08	RW	DCC22DR0	48	#		88			C8	
PRT2IE	09	RW	DCC22DR1	49	W		89			C9	
PRT2GS	0A	RW	DCC22DR2	4A	RW		8A			CA	
PRT2DM2	0B	RW	DCC22CR0	4B	#		8B			CB	
PRT3DR	0C	RW	DCC23DR0	4C	#		8C			CC	
PRT3IE	0D	RW	DCC23DR1	4D	W		8D			CD	
PRT3GS	0E	RW	DCC23DR2	4E	RW		8E			CE	
PRT3DM2	0F	RW	DCC23CR0	4F	#		8F			CF	
PRT4DR	10	RW		50		ASD20CR0	90	RW	CUR_PP	D0	RW
PRT4IE	11	RW		51		ASD20CR1	91	RW	STK_PP	D1	RW
PRT4GS	12	RW		52		ASD20CR2	92	RW		D2	
PRT4DM2	13	RW		53		ASD20CR3	93	RW	IDX_PP	D3	RW
PRT5DR	14	RW		54		ASC21CR0	94	RW	MVR_PP	D4	RW
PRT5IE	15	RW		55		ASC21CR1	95	RW	MVW_PP	D5	RW
PRT5GS	16	RW		56		ASC21CR2	96	RW	I2C0_CFG	D6	RW
PRT5DM2	17	RW		57		ASC21CR3	97	RW	I2C0_SCR	D7	#
	18			58			98		I2C0_DR	D8	RW
	19			59			99		I2C0_MSCR	D9	#
	1A			5A			9A		INT_CLR0	DA	RW
	1B			5B			9B		INT_CLR1	DB	RW
	1C			5C			9C		INT_CLR2	DC	RW
	1D			5D			9D		INT_CLR3	DD	RW
	1E			5E			9E		INT_MSK3	DE	RW
	1F			5F			9F		INT_MSK2	DF	RW
DBC00DR0	20	#	AMX_IN	60	RW	DEC0_DH	A0	RC	INT_MSK0	E0	RW
DBC00DR1	21	W	AMUX_CFG	61	RW	DEC0_DL	A1	RC	INT_MSK1	E1	RW
DBC00DR2	22	RW	CLK_CR3	62	RW	DEC1_DH	A2	RC	INT_VC	E2	RC
DBC00CR0	23	#	ARF_CR	63	RW	DEC1_DL	A3	RC	RES_WDT	E3	W
DBC01DR0	24	#	CMP_CR0	64	#	DEC2_DH	A4	RC		E4	
DBC01DR1	25	W	ASY_CR	65	#	DEC2_DL	A5	RC		E5	
DBC01DR2	26	RW	CMP_CR1	66	RW	DEC3_DH	A6	RC	DEC_CR0*	E6	RW
DBC01CR0	27	#		67		DEC3_DL	A7	RC	DEC_CR1*	E7	RW
DCC02DR0	28	#		68		MUL1_X	A8	W	MUL0_X	E8	W
DCC02DR1	29	W		69		MUL1_Y	A9	W	MUL0_Y	E9	W
DCC02DR2	2A	RW	SADC_DH	6A	RW	MUL1_DH	AA	R	MUL0_DH	EA	R
DCC02CR0	2B	#	SADC_DL	6B	RW	MUL1_DL	AB	R	MUL0_DL	EB	R
DCC03DR0	2C	#	TMP_DR0	6C	RW	ACC1_DR1	AC	RW	ACC0_DR1	EC	RW
DCC03DR1	2D	W	TMP_DR1	6D	RW	ACC1_DR0	AD	RW	ACC0_DR0	ED	RW
DCC03DR2	2E	RW	TMP_DR2	6E	RW	ACC1_DR3	AE	RW	ACC0_DR3	EE	RW
DCC03CR0	2F	#	TMP_DR3	6F	RW	ACC1_DR2	AF	RW	ACC0_DR2	EF	RW
DBC10DR0	30	#	ACB00CR3	70	RW	RDI0RI	B0	RW		F0	
DBC10DR1	31	W	ACB00CR0	71	RW	RDI0SYN	B1	RW		F1	
DBC10DR2	32	RW	ACB00CR1	72	RW	RDI0IS	B2	RW		F2	
DBC10CR0	33	#	ACB00CR2	73	RW	RDI0LT0	B3	RW		F3	
DBC11DR0	34	#	ACB01CR3	74	RW	RDI0LT1	B4	RW		F4	
DBC11DR1	35	W	ACB01CR0	75	RW	RDI0RO0	B5	RW		F5	
DBC11DR2	36	RW	ACB01CR1	76	RW	RDI0RO1	B6	RW		F6	
DBC11CR0	37	#	ACB01CR2	77	RW	RDI0DSM	B7	RW	CPU_F	F7	RL
DCC12DR0	38	#		78		RDI1RI	B8	RW		F8	
DCC12DR1	39	W		79		RDI1SYN	B9	RW		F9	
DCC12DR2	3A	RW		7A		RDI1IS	BA	RW		FA	
DCC12CR0	3B	#		7B		RDI1LT0	BB	RW		FB	
DCC13DR0	3C	#		7C		RDI1LT1	BC	RW	DAC1_D	FC	RW
DCC13DR1	3D	W		7D		RDI1RO0	BD	RW	DAC0_D	FD	RW
DCC13DR2	3E	RW		7E		RDI1RO1	BE	RW	CPU_SCR1	FE	#
DCC13CR0	3F	#		7F		RDI1DSM	BF	RW	CPU_SCR0	FF	#

Blank fields are Reserved and should not be accessed. # Access is bit specific. *Address has a dual purpose, see “Mapping Exceptions” on page 251

Table 16. CY8C28x43 Register Map Bank 0 Table: User Space

Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access
PRT0DR	00	RW	DBC20DR0	40	#	ASC10CR0	80	RW	RDI2RI	C0	RW
PRT0IE	01	RW	DBC20DR1	41	W	ASC10CR1	81	RW	RDI2SYN	C1	RW
PRT0GS	02	RW	DBC20DR2	42	RW	ASC10CR2	82	RW	RDI2IS	C2	RW
PRT0DM2	03	RW	DBC20CR0	43	#	ASC10CR3	83	RW	RDI2LT0	C3	RW
PRT1DR	04	RW	DBC21DR0	44	#	ASD11CR0	84	RW	RDI2LT1	C4	RW
PRT1IE	05	RW	DBC21DR1	45	W	ASD11CR1	85	RW	RDI2RO0	C5	RW
PRT1GS	06	RW	DBC21DR2	46	RW	ASD11CR2	86	RW	RDI2RO1	C6	RW
PRT1DM2	07	RW	DBC21CR0	47	#	ASD11CR3	87	RW	RDI2DSM	C7	RW
PRT2DR	08	RW	DCC22DR0	48	#	ASC12CR0	88	RW		C8	
PRT2IE	09	RW	DCC22DR1	49	W	ASC12CR1	89	RW		C9	
PRT2GS	0A	RW	DCC22DR2	4A	RW	ASC12CR2	8A	RW		CA	
PRT2DM2	0B	RW	DCC22CR0	4B	#	ASC12CR3	8B	RW		CB	
PRT3DR	0C	RW	DCC23DR0	4C	#	ASD13CR0	8C	RW		CC	
PRT3IE	0D	RW	DCC23DR1	4D	W	ASD13CR1	8D	RW		CD	
PRT3GS	0E	RW	DCC23DR2	4E	RW	ASD13CR2	8E	RW		CE	
PRT3DM2	0F	RW	DCC23CR0	4F	#	ASD13CR3	8F	RW		CF	
PRT4DR	10	RW		50		ASD20CR0	90	RW	CUR_PP	D0	RW
PRT4IE	11	RW		51		ASD20CR1	91	RW	STK_PP	D1	RW
PRT4GS	12	RW		52		ASD20CR2	92	RW		D2	
PRT4DM2	13	RW		53		ASD20CR3	93	RW	IDX_PP	D3	RW
PRT5DR	14	RW		54		ASC21CR0	94	RW	MVR_PP	D4	RW
PRT5IE	15	RW		55		ASC21CR1	95	RW	MVW_PP	D5	RW
PRT5GS	16	RW		56		ASC21CR2	96	RW	I2C0_CFG	D6	RW
PRT5DM2	17	RW		57		ASC21CR3	97	RW	I2C0_SCR	D7	#
	18			58		ASD22CR0	98	RW	I2C0_DR	D8	RW
	19			59		ASD22CR1	99	RW	I2C0_MSCR	D9	#
	1A			5A		ASD22CR2	9A	RW	INT_CLR0	DA	RW
	1B			5B		ASD22CR3	9B	RW	INT_CLR1	DB	RW
	1C			5C		ASC23CR0	9C	RW	INT_CLR2	DC	RW
	1D			5D		ASC23CR1	9D	RW	INT_CLR3	DD	RW
	1E			5E		ASC23CR2	9E	RW	INT_MSK3	DE	RW
	1F			5F		ASC23CR3	9F	RW	INT_MSK2	DF	RW
DBC00DR0	20	#	AMX_IN	60	RW	DEC0_DH	A0	RC	INT_MSK0	E0	RW
DBC00DR1	21	W	AMUX_CFG	61	RW	DEC0_DL	A1	RC	INT_MSK1	E1	RW
DBC00DR2	22	RW	CLK_CR3	62	RW	DEC1_DH	A2	RC	INT_VC	E2	RC
DBC00CR0	23	#	ARF_CR	63	RW	DEC1_DL	A3	RC	RES_WDT	E3	W
DBC01DR0	24	#	CMP_CR0	64	#	DEC2_DH	A4	RC	I2C1_SCR	E4	#
DBC01DR1	25	W	ASY_CR	65	#	DEC2_DL	A5	RC	I2C1_MSCR	E5	#
DBC01DR2	26	RW	CMP_CR1	66	RW	DEC3_DH	A6	RC	DEC_CR0*	E6	RW
DBC01CR0	27	#	I2C1_DR	67	RW	DEC3_DL	A7	RC	DEC_CR1*	E7	RW
DCC02DR0	28	#		68		MUL1_X	A8	W	MUL0_X	E8	W
DCC02DR1	29	W		69		MUL1_Y	A9	W	MUL0_Y	E9	W
DCC02DR2	2A	RW	SADC_DH	6A	RW	MUL1_DH	AA	R	MUL0_DH	EA	R
DCC02CR0	2B	#	SADC_DL	6B	RW	MUL1_DL	AB	R	MUL0_DL	EB	R
DCC03DR0	2C	#	TMP_DR0	6C	RW	ACC1_DR1	AC	RW	ACC0_DR1	EC	RW
DCC03DR1	2D	W	TMP_DR1	6D	RW	ACC1_DR0	AD	RW	ACC0_DR0	ED	RW
DCC03DR2	2E	RW	TMP_DR2	6E	RW	ACC1_DR3	AE	RW	ACC0_DR3	EE	RW
DCC03CR0	2F	#	TMP_DR3	6F	RW	ACC1_DR2	AF	RW	ACC0_DR2	EF	RW
DBC10DR0	30	#	ACB00CR3	70	RW	RDI0RI	B0	RW		F0	
DBC10DR1	31	W	ACB00CR0	71	RW	RDI0SYN	B1	RW		F1	
DBC10DR2	32	RW	ACB00CR1	72	RW	RDI0IS	B2	RW		F2	
DBC10CR0	33	#	ACB00CR2	73	RW	RDI0LT0	B3	RW		F3	
DBC11DR0	34	#	ACB01CR3	74	RW	RDI0LT1	B4	RW		F4	
DBC11DR1	35	W	ACB01CR0	75	RW	RDI0RO0	B5	RW		F5	
DBC11DR2	36	RW	ACB01CR1	76	RW	RDI0RO1	B6	RW		F6	
DBC11CR0	37	#	ACB01CR2	77	RW	RDI0DSM	B7	RW	CPU_F	F7	RL
DCC12DR0	38	#	ACB02CR3	78	RW	RDI1RI	B8	RW		F8	
DCC12DR1	39	W	ACB02CR0	79	RW	RDI1SYN	B9	RW		F9	
DCC12DR2	3A	RW	ACB02CR1	7A	RW	RDI1IS	BA	RW		FA	
DCC12CR0	3B	#	ACB02CR2	7B	RW	RDI1LT0	BB	RW		FB	
DCC13DR0	3C	#	ACB03CR3	7C	RW	RDI1LT1	BC	RW		FC	
DCC13DR1	3D	W	ACB03CR0	7D	RW	RDI1RO0	BD	RW		FD	
DCC13DR2	3E	RW	ACB03CR1	7E	RW	RDI1RO1	BE	RW	CPU_SCR1	FE	#
DCC13CR0	3F	#	ACB03CR2	7F	RW	RDI1DSM	BF	RW	CPU_SCR0	FF	#

Blank fields are Reserved and should not be accessed. # Access is bit specific. *Address has a dual purpose, see “Mapping Exceptions” on page 251

Table 19. CY8C28x45 Register Map Bank 1 Table: Configuration Space

Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access
PRT0DM0	00	RW	DBC20FN	40	RW		80	RW	RDI2RI	C0	RW
PRT0DM1	01	RW	DBC20IN	41	RW	SADC_TSCMPL	81	RW	RDI2SYN	C1	RW
PRT0IC0	02	RW	DBC20OU	42	RW	SADC_TSCMPH	82	RW	RDI2IS	C2	RW
PRT0IC1	03	RW	DBC20CR1	43	RW	ACE_AMD_CR1	83	RW	RDI2LT0	C3	RW
PRT1DM0	04	RW	DBC21FN	44	RW		84	RW	RDI2LT1	C4	RW
PRT1DM1	05	RW	DBC21IN	45	RW	ACE_PWM_CR	85	RW	RDI2RO0	C5	RW
PRT1IC0	06	RW	DBC21OU	46	RW	ACE_ADC0_CR	86	RW	RDI2RO1	C6	RW
PRT1IC1	07	RW	DBC21CR1	47	RW	ACE_ADC1_CR	87	RW	RDI2DSM	C7	RW
PRT2DM0	08	RW	DCC22FN	48	RW		88	RW		C8	
PRT2DM1	09	RW	DCC22IN	49	RW	ACE_CLK_CR0	89	RW		C9	
PRT2IC0	0A	RW	DCC22OU	4A	RW	ACE_CLK_CR1	8A	RW		CA	
PRT2IC1	0B	RW	DCC22CR1	4B	RW	ACE_CLK_CR3	8B	RW		CB	
PRT3DM0	0C	RW	DCC23FN	4C	RW		8C	RW		CC	
PRT3DM1	0D	RW	DCC23IN	4D	RW	ACE01CR1	8D	RW		CD	
PRT3IC0	0E	RW	DCC23OU	4E	RW	ACE01CR2	8E	RW		CE	
PRT3IC1	0F	RW	DCC23CR1	4F	RW	ASE11CR0	8F	RW		CF	
PRT4DM0	10	RW		50			90		GDI_O_IN	D0	RW
PRT4DM1	11	RW		51		DEC0_CR0	91	RW	GDI_E_IN	D1	RW
PRT4IC0	12	RW		52		DEC_CR3	92	RW	GDI_O_OU	D2	RW
PRT4IC1	13	RW		53			93		GDI_E_OU	D3	RW
PRT5DM0	14	RW		54			94		DEC0_CR	D4	RW
PRT5DM1	15	RW		55		DEC1_CR0	95	RW	DEC1_CR	D5	RW
PRT5IC0	16	RW		56		DEC_CR4	96	RW	DEC2_CR	D6	RW
PRT5IC1	17	RW		57			97		DEC3_CR	D7	RW
	18			58			98		MUX_CR0	D8	RW
	19			59		DEC2_CR0	99	RW	MUX_CR1	D9	RW
	1A			5A		DEC_CR5	9A	RW	MUX_CR2	DA	RW
	1B			5B			9B		MUX_CR3	DB	RW
	1C			5C			9C		IDAC_CR1	DC	RW
	1D			5D		DEC3_CR0	9D	RW	OSC_GO_EN	DD	RW
	1E			5E			9E		OSC_CR4	DE	RW
	1F			5F			9F		OSC_CR3	DF	RW
DBC00FN	20	RW	CLK_CR0	60	RW	GDI_O_IN_CR	A0	RW	OSC_CR0	E0	RW
DBC00IN	21	RW	CLK_CR1	61	RW	GDI_E_IN_CR	A1	RW	OSC_CR1	E1	RW
DBC00OU	22	RW	ABF_CR0	62	RW	GDI_O_OU_CR	A2	RW	OSC_CR2	E2	RW
DBC00CR1	23	RW	AMD_CR0	63	RW	GDI_E_OU_CR	A3	RW	VLT_CR	E3	RW
DBC01FN	24	RW	CMP_GO_EN	64	RW	RTC_H	A4	RW	VLT_CMP	E4	RW
DBC01IN	25	RW	CMP_GO_EN1	65	RW	RTC_M	A5	RW	ADC0_TR	E5	RW
DBC01OU	26	RW	AMD_CR1	66	RW	RTC_S	A6	RW	ADC1_TR	E6	RW
DBC01CR1	27	RW	ALT_CR0	67	RW	RTC_CR	A7	RW	IDAC_CR2	E7	RW
DCC02FN	28	RW	ALT_CR1	68	RW	SADC_CR0	A8	RW	IMO_TR	E8	RW
DCC02IN	29	RW	CLK_CR2	69	RW	SADC_CR1	A9	RW	ILO_TR	E9	RW
DCC02OU	2A	RW	AMUX_CFG1	6A	RW	SADC_CR2	AA	RW	BDG_TR	EA	RW
DCC02CR1	2B	RW	I2C1_CFG	6B	RW	SADC_CR3	AB	RW	ECO_TR	EB	RW
DCC03FN	2C	RW	TMP_DR0	6C	RW	SADC_CR4	AC	RW	MUX_CR4	EC	RW
DCC03IN	2D	RW	TMP_DR1	6D	RW	I2C0_ADDR	AD	RW	MUX_CR5	ED	RW
DCC03OU	2E	RW	TMP_DR2	6E	RW	I2C1_ADDR	AE	RW		EE	
DCC03CR1	2F	RW	TMP_DR3	6F	RW	AMUX_CLK	AF	RW		EF	
DBC10FN	30	RW		70		RDI0RI	B0	RW		F0	
DBC10IN	31	RW	SADC_TSCR0	71	RW	RDI0SYN	B1	RW		F1	
DBC10OU	32	RW	SADC_TSCR1	72	RW	RDI0IS	B2	RW		F2	
DBC10CR1	33	RW	ACE_AMD_CR0	73	RW	RDI0LT0	B3	RW		F3	
DBC11FN	34	RW		74		RDI0LT1	B4	RW		F4	
DBC11IN	35	RW	ACE_AMX_IN	75	RW	RDI0RO0	B5	RW		F5	
DBC11OU	36	RW	ACE_CMP_CR0	76	RW	RDI0RO1	B6	RW		F6	
DBC11CR1	37	RW	ACE_CMP_CR1	77	RW	RDIODSM	B7	RW	CPU_F	F7	RL
DCC12FN	38	RW		78		RDI1RI	B8	RW		F8	
DCC12IN	39	RW	ACE_CMP_GI_EN	79	RW	RDI1SYN	B9	RW		F9	
DCC12OU	3A	RW	ACE_ALT_CR0	7A	RW	RDI1IS	BA	RW	FLS_PR1	FA	RW
DCC12CR1	3B	RW	ACE_ABF_CR0	7B	RW	RDI1LT0	BB	RW		FB	
DCC13FN	3C	RW		7C		RDI1LT1	BC	RW		FC	
DCC13IN	3D	RW	ACE0_CR1	7D	RW	RDI1RO0	BD	RW	IDAC_CR0	FD	RW
DCC13OU	3E	RW	ACE0_CR2	7E	RW	RDI1RO1	BE	RW	CPU_SCR1	FE	#
DCC13CR1	3F	RW	ACE0_CR3	7F	RW	RDI1DSM	BF	RW	CPU_SCR0	FF	#

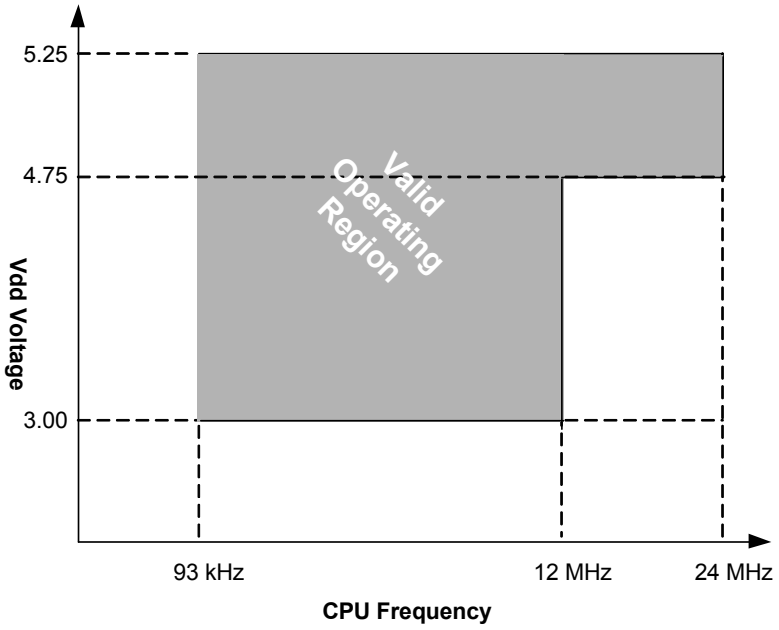
Blank fields are Reserved and should not be accessed. # Access is bit specific. *Address has a dual purpose, see “Mapping Exceptions” on page 251

Electrical Specifications

This section presents the DC and AC electrical specifications of the CY8C28xxx PSoC devices. For the most up to date electrical specifications, confirm that you have the most recent datasheet by going to the web at http//www.cypress.com.

Specifications are valid for –40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Specifications for devices running at greater than 12 MHz are valid for –40 °C ≤ T_A ≤ 70 °C and T_J ≤ 82 °C.

Figure 8. Voltage versus CPU Frequency



Absolute Maximum Ratings

Table 22. Absolute Maximum Ratings

Symbol	Description	Min	Typ	Max	Units	Notes
T_{STG}	Storage temperature	–55	25	+100	°C	Higher storage temperatures reduce data retention time. Recommended storage temperature is +25°C ± 25°C. Extended duration storage temperatures above 65°C degrade reliability.
$T_{BAKETEMP}$	Bake temperature	–	125	See Package label	°C	
$t_{BAKETIME}$	Bake time	See package label	-	72	Hours	
T_A	Ambient temperature with power applied	-40	–	+85	°C	
V_{DD}	Supply voltage on V_{DD} relative to V_{SS}	-0.5	–	+6.0	V	
V_{IO}	DC input voltage	V_{SS} – 0.5	–	V_{DD} + 0.5	V	
V_{IOZ}	DC voltage applied to tri-state	V_{SS} – 0.5	–	V_{DD} + 0.5	V	
I_{MIO}	Maximum current into any port pin	-25	–	+50	mA	
I_{MAIO}	Maximum current into any port pin configured as analog driver	-50	–	+50	mA	
ESD	Electro static discharge voltage	2000	–	–	V	Human Body Model ESD.
LU	Latch up current	–	–	200	mA	

Operating Temperature

Table 23. Operating Temperature

Symbol	Description	Min	Typ	Max	Units	Notes
T_A	Ambient temperature	-40	–	+85	°C	
T_J	Junction temperature	-40	–	+100	°C	The temperature rise from ambient to junction is package specific. See Thermal Impedances on page 72. The user must limit the power consumption to comply with this requirement.

DC GPIO Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 25. DC GPIO Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
R_{PU}	Pull-up resistor	4	5.6	8	kΩ	
R_{PD}	Pull-down resistor	4	5.6	8	kΩ	
V_{OH}	High output level	V_{DD} – 1.0	–	–	V	I_{OH} = 10 mA, V_{DD} = 4.75 to 5.25 V (8 total loads, 4 on even port pins (for example, P0[2], P1[4]), 4 on odd port pins (for example, P0[3], P1[5])). 80 mA maximum combined I_{OH} budget.
V_{OL}	Low output level	–	–	0.75	V	I_{OL} = 25 mA, V_{DD} = 4.75 to 5.25 V (8 total loads, 4 on even port pins (for example, P0[2], P1[4]), 4 on odd port pins (for example, P0[3], P1[5])). 150 mA maximum combined I_{OL} budget.
I_{OH}	High level source current	10	–	–	mA	V_{OH} = V_{DD} – 1.0 V, see the limitations of the total current in the note for V_{OH}.
I_{OL}	Low level sink current	25	–	–	mA	V_{OL} = 0.75 V, see the limitations of the total current in the note for V_{OL}.
V_{IL}	Input low level	–	–	0.8	V	V_{DD} = 3.0 to 5.25.
V_{IH}	Input high level	2.1	–	–	V	V_{DD} = 3.0 to 5.25.
V_H	Input hysteresis	–	60	–	mV	
I_{IL}	Input leakage (absolute value)	–	1	–	nA	Gross tested to 1 μA.
C_{IN}	Capacitive load on pins as input	–	3.5	10	pF	Package and pin dependent. Temp = 25 °C.
C_{OUT}	Capacitive load on pins as output	–	3.5	10	pF	Package and pin dependent. Temp = 25 °C.

Table 34. 5-V DC Analog Reference Specifications *(continued)*

Reference ARF_CR [5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Typ	Max	Units
0b101	RefPower = High Opamp bias = High	V_{REFHI}	Ref high	P2[4] + Bandgap (P2[4] = V_{DD}/2)	P2[4] + 1.218	P2[4] + 1.283	P2[4] + 1.344	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	–
		V_{REFLO}	Ref low	P2[4] – Bandgap (P2[4] = V_{DD}/2)	P2[4] – 1.329	P2[4] – 1.297	P2[4] – 1.265	V
	RefPower = High Opamp bias = Low	V_{REFHI}	Ref high	P2[4] + Bandgap (P2[4] = V_{DD}/2)	P2[4] + 1.225	P2[4] + 1.287	P2[4] + 1.346	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	–
		V_{REFLO}	Ref low	P2[4] – Bandgap (P2[4] = V_{DD}/2)	P2[4] – 1.330	P2[4] – 1.301	P2[4] – 1.271	V
	RefPower = Medium Opamp bias = High	V_{REFHI}	Ref high	P2[4] + Bandgap (P2[4] = V_{DD}/2)	P2[4] + 1.226	P2[4] + 1.288	P2[4] + 1.346	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	–
		V_{REFLO}	Ref low	P2[4] – Bandgap (P2[4] = V_{DD}/2)	P2[4] – 1.330	P2[4] – 1.302	P2[4] – 1.272	V
	RefPower = Medium Opamp bias = Low	V_{REFHI}	Ref high	P2[4] + Bandgap (P2[4] = V_{DD}/2)	P2[4] + 1.227	P2[4] + 1.289	P2[4] + 1.347	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	–
		V_{REFLO}	Ref low	P2[4] – Bandgap (P2[4] = V_{DD}/2)	P2[4] – 1.331	P2[4] – 1.303	P2[4] – 1.273	V
0b110	RefPower = High Opamp bias = High	V_{REFHI}	Ref high	2 × Bandgap	2.506	2.597	2.674	V
		V_{AGND}	AGND	Bandgap	1.263	1.302	1.336	V
		V_{REFLO}	Ref low	V_{SS}	V_{SS}	V_{SS} + 0.006	V_{SS} + 0.014	V
	RefPower = High Opamp bias = Low	V_{REFHI}	Ref high	2 × Bandgap	2.508	2.595	2.675	V
		V_{AGND}	AGND	Bandgap	1.263	1.302	1.336	V
		V_{REFLO}	Ref low	V_{SS}	V_{SS}	V_{SS} + 0.003	V_{SS} + 0.008	V
	RefPower = Medium Opamp bias = High	V_{REFHI}	Ref high	2 × Bandgap	2.508	2.595	2.676	V
		V_{AGND}	AGND	Bandgap	1.263	1.302	1.336	V
		V_{REFLO}	Ref low	V_{SS}	V_{SS}	V_{SS} + 0.002	V_{SS} + 0.005	V
	RefPower = Medium Opamp bias = Low	V_{REFHI}	Ref high	2 × Bandgap	2.508	2.596	2.677	V
		V_{AGND}	AGND	Bandgap	1.263	1.302	1.336	V
		V_{REFLO}	Ref low	V_{SS}	V_{SS}	V_{SS} + 0.001	V_{SS} + 0.003	V

DC IDAC Specifications

Table 39. DC IDAC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
IDAC_DNL	Differential nonlinearity	–5.0	2.0	5.0	LSB	Valid for all 3 current ranges
IDAC_INL	Integral nonlinearity	–5.0	2.0	5.0	LSB	Valid for all 3 current ranges
IDAC_Gain	Gain per bit – Range 1 (91 µA)	283	357	447	nA	Measured at full scale
	Gain per bit – Range 2 (318 µA)	985	1250	1532	nA	
	Gain per bit – Range 3 (637 µA)	1959	2500	3056	nA	
IDACOffset	Offset at Code 0 vs LSB Ideal – Range 1 (91 µA)		2.0%	20%	%	Measured as a % of LSB (Current @ Code 0)/(LSB Ideal Current)
	Offset at Code 0 vs LSB Ideal – Range 2 (318 µA)		1.0%	10%	%	
	Offset at Code 0 vs LSB Ideal – Range 3 (637 µA)		1.0%	10%	%	

AC Electrical Characteristics

AC Chip-Level Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 43. AC Chip-Level Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{IMO}	Internal Main Oscillator Frequency	23.4	24	24.6[21]	MHz	Trimmed. Utilizing factory trim values. SLIMO Mode = 0.
F_{IMO6}	Internal Main Oscillator Frequency for 6 MHz	5.5	6	6.5[21]	MHz	Trimmed for 5 V or 3.3 V operation using factory trim values. SLIMO Mode = 1.
F_{CPU1}	CPU Frequency (5 V Nominal)	0.091	24	24.6[21]	MHz	Trimmed. Utilizing factory trim values. SLIMO mode = 0.
F_{CPU2}	CPU Frequency (3.3 V Nominal)	0.091	12	12.3[22]	MHz	Trimmed. Utilizing factory trim values. SLIMO mode = 0.
F_{BLK5}	Digital PSoC Block Frequency	0	–	49.2[21, 23]	MHz	4.75 V< V_{DD} <5.25 V
F_{BLK33}	Digital PSoC Block Frequency	0	24	24.6[23]	MHz	3.0 V<V_{DD}<3.6 V
F_{32K1}	Internal Low Speed Oscillator Frequency	15	32	64	kHz	Trimmed. Utilizing factory trim values.
F_{32K2}	External Crystal Oscillator	–	32.768	–	kHz	Accuracy is capacitor and crystal dependent. 50% duty cycle.
F_{32K_U}	Internal Low Speed Oscillator Untrimmed Frequency	5	–	100	kHz	After a reset and before the m8c starts to run, the ILO is not trimmed. See the System Resets section of the PSoC Technical Reference manual for details on timing this.
F_{PLL}	PLL Frequency	–	23.986	–	MHz	Multiple (x732) of crystal frequency.
$t_{PLLSLEW}$	PLL Lock Time	0.5	–	10	ms	
$t_{PLLSLEWSLOW}$	PLL Lock Time for Low Gain Setting	0.5	–	50	ms	
T_{OS}	External Crystal Oscillator Startup to 1%	–	1700	2620	ms	
T_{OSACC}	External Crystal Oscillator Startup to 100 ppm	–	2800	3800	ms	The crystal oscillator frequency is within 100 ppm of its final value by the end of the T_{osacc} period. Correct operation assumes a properly loaded 1 µW maximum drive level 32.768 kHz crystal. 3.0 V ≤ V_{DD} ≤ 5.5 V, –40 °C ≤ T_A ≤ 85 °C.

Notes
21. 4.75 V < V_{DD} < 5.25 V.
22. 3.0 V < V_{DD} < 3.6 V. See application note Adjusting PSoC® Trims for 3.3 V and 2.7 V Operation – AN2012 for information on trimming for operation at 3.3 V.
23. See the individual user module datasheets for information on maximum frequencies for user modules.

Table 43. AC Chip-Level Specifications *(continued)*

Symbol	Description	Min	Typ	Max	Units	Notes
t_{XRST}	External Reset Pulse Width	10	–	–	µs	
DC24M	24 MHz Duty Cycle	40	50	60	%	
DC_{ILO}	Internal Low Speed Oscillator Duty Cycle	20	50	80	%	
Fout48M	48 MHz Output Frequency	46.8	48.0	49.2[24,25]	MHz	Trimmed. Utilizing factory trim values.
F_{MAX}	Maximum Frequency of Signal on Row Input or Row Output.	–	–	12.3	MHz	
$SR_{POWERUP}$	Supply Ramp Time	0	–	–	µs	
$t_{POWERUP}$	Time for POR Release to Code Execution	–	16	100	ms	
t_{jit_IMO} [26]	24 MHz IMO cycle-to-cycle jitter (RMS)	–	200	1300	ps	
	24 MHz IMO long term N cycle-to-cycle jitter (RMS)	–	300	1300	ps	N = 32
	24 MHz IMO period jitter (RMS)	–	200	800	ps	
t_{jit_PLL} [26]	24 MHz IMO cycle-to-cycle jitter (RMS)	–	200	1100	ps	
	24 MHz IMO long term N cycle-to-cycle jitter (RMS)	–	400	2800	ps	N = 32
	24 MHz IMO period jitter (RMS)	–	200	1400	ps	

Notes
24. 4.75 V < V_{DD} < 5.25 V.
25. 3.0 V < V_{DD} < 3.6 V. See application note Adjusting PSoC® Trims for 3.3 V and 2.7 V Operation – AN2012 for information on trimming for operation at 3.3 V.
26. Refer to Cypress Jitter Specifications application note, Understanding Datasheet Jitter Specifications for Cypress Timing Products – AN5054 for more information.

Figure 18. 28-pin SSOP (210 Mils) O28.21 Package Outline, 51-85079

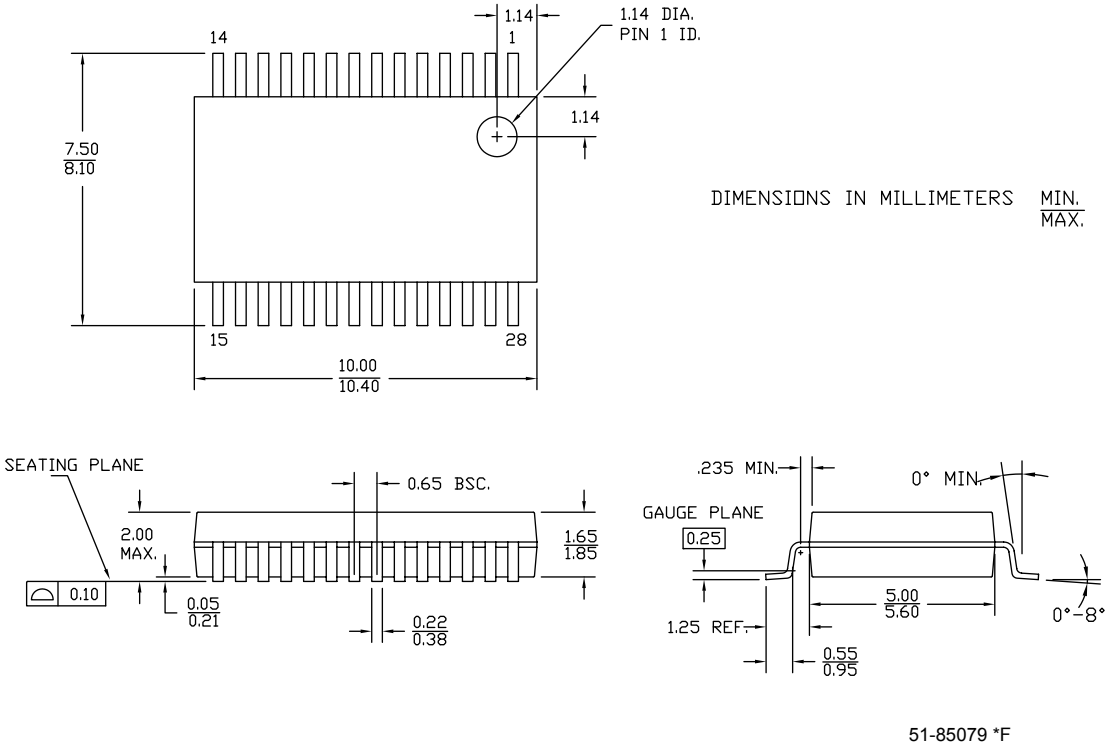


Figure 19. 44-pin TQFP (10 × 10 × 1.4 mm) A44S Package Outline, 51-85064

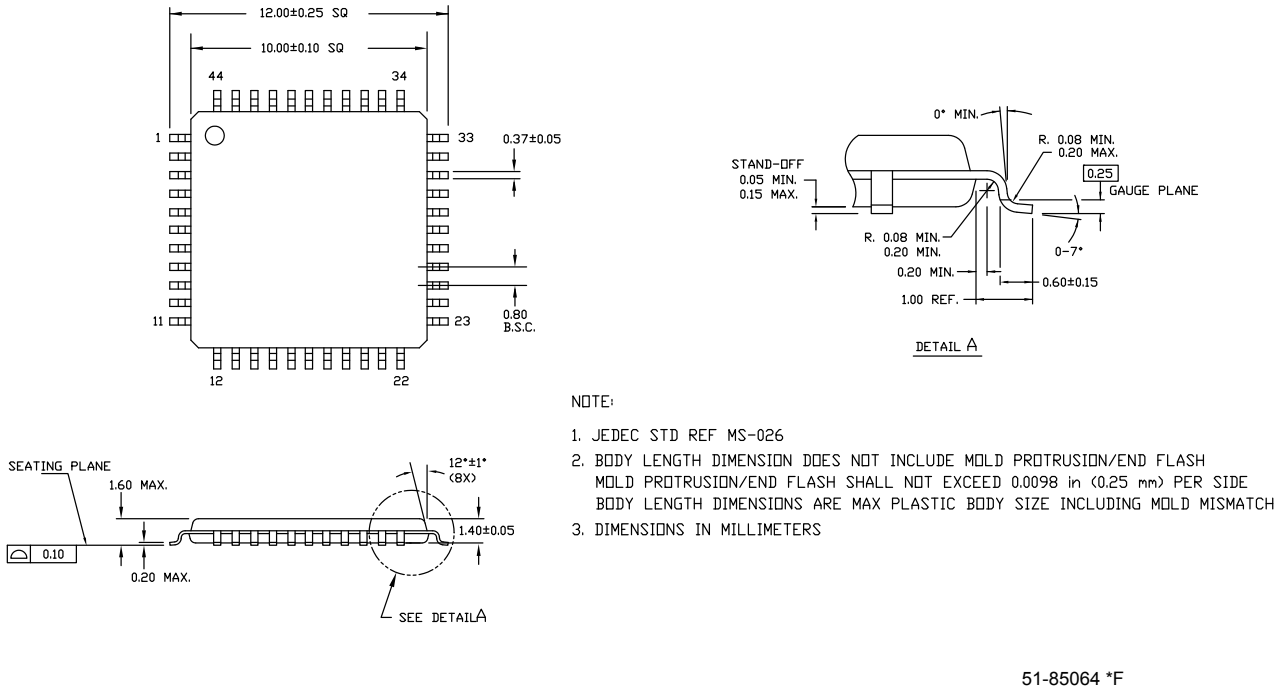
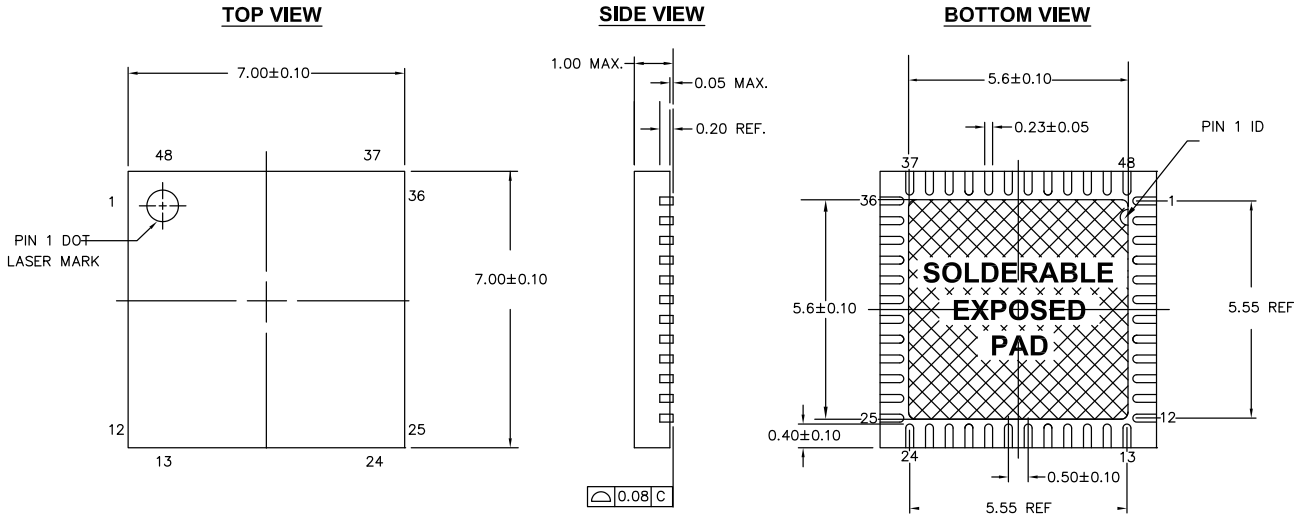


Figure 20. 48-pin QFN (7 × 7 × 1.0 mm) LT48D 5.6 × 5.6 E-Pad (Sawn Type) Package Outline, 001-45616



NOTES:
1. ▨ HATCH AREA IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC#: MO−220
3. PACKAGE WEIGHT: REFER TO PMDD SPEC.
4. ALL DIMENSIONS ARE IN MM [MIN/MAX]
5. PACKAGE CODE

PART #	DESCRIPTION
LT48D	LEAD FREE

001-45616 *E

Important Note For information on the preferred dimensions for mounting QFN packages, see the following application note, *Design Guidelines for Cypress Quad Flat No Extended Lead (QFN) Packaged Devices – AN72845* available at http://www.cypress.com.

Ordering Information

The following table lists the CY8C28xxx PSoC devices key package features and ordering codes.

Package	Ordering Code	Temperature Range	CapSense	Digital Blocks	Regular Analog Blocks	Limited Analog Blocks	HW I^2C	Decimators	10-bit SAR ADC	Digital I/O Pins	Analog Inputs	Analog Outputs	Flash (KBytes)	RAM (KBytes)	XRES Pin
28-Pin (210-Mil) SSOP	CY8C28403-24PVXI	–40 °C to 85 °C	N	12	0	0	2	0	Y	24	8	0	16	1	Y
28-Pin (210-Mil) SSOP (Tape and Reel)	CY8C28403-24PVXIT	–40 °C to 85 °C	N	12	0	0	2	0	Y	24	8	0	16	1	Y
28-Pin (210-Mil) SSOP	CY8C28413-24PVXI	–40 °C to 85 °C	Y	12	0	4	1	2	Y	24	24	0	16	1	Y
28-Pin (210-Mil) SSOP (Tape and Reel)	CY8C28413-24PVXIT	–40 °C to 85 °C	Y	12	0	4	1	2	Y	24	24	0	16	1	Y
44-Pin TQFP	CY8C28513-24AXI	–40 °C to 85 °C	Y	12	0	4	1	2	Y	40	40	0	16	1	Y
44-Pin TQFP (Tape and Reel)	CY8C28513-24AXIT	–40 °C to 85 °C	Y	12	0	4	1	2	Y	40	40	0	16	1	Y
48-Pin Sawn QFN	CY8C28623-24LTXI	–40 °C to 85 °C	N	12	6	0	2	2	N	44	10	2	16	1	Y
48-Pin Sawn QFN (Tape and Reel)	CY8C28623-24LTXIT	–40 °C to 85 °C	N	12	6	0	2	2	N	44	10	2	16	1	Y
28-Pin (210-Mil) SSOP	CY8C28433-24PVXI	–40 °C to 85 °C	Y	12	6	4	1	4	Y	24	24	2	16	1	Y
28-Pin (210-Mil) SSOP (Tape and Reel)	CY8C28433-24PVXIT	–40 °C to 85 °C	Y	12	6	4	1	4	Y	24	24	2	16	1	Y
20-Pin (210-Mil) SSOP	CY8C28243-24PVXI	–40 °C to 85 °C	N	12	12	0	2	4	Y	16	16	4	16	1	Y
20-Pin (210-Mil) SSOP (Tape and Reel)	CY8C28243-24PVXIT	–40 °C to 85 °C	N	12	12	0	2	4	Y	16	16	4	16	1	Y
48-Pin Sawn QFN	CY8C28643-24LTXI	–40 °C to 85 °C	N	12	12	0	2	4	Y	44	44	4	16	1	Y
48-Pin Sawn QFN (Tape and Reel)	CY8C28643-24LTXIT	–40 °C to 85 °C	N	12	12	0	2	4	Y	44	44	4	16	1	Y
28-Pin (210-Mil) SSOP	CY8C28445-24PVXI	–40 °C to 85 °C	Y	12	12	4	2	4	Y	24	24	4	16	1	Y
28-Pin (210-Mil) SSOP (Tape and Reel)	CY8C28445-24PVXIT	–40 °C to 85 °C	Y	12	12	4	2	4	Y	24	24	4	16	1	Y
44-Pin TQFP	CY8C28545-24AXI	–40 °C to 85 °C	Y	12	12	4	2	4	Y	40	40	4	16	1	Y
44-Pin TQFP (Tape and Reel)	CY8C28545-24AXIT	–40 °C to 85 °C	Y	12	12	4	2	4	Y	40	40	4	16	1	Y
48-Pin Sawn QFN	CY8C28645-24LTXI	–40 °C to 85 °C	Y	12	12	4	2	4	Y	44	44	4	16	1	Y
48-Pin Sawn QFN (Tape and Reel)	CY8C28645-24LTXIT	–40 °C to 85 °C	Y	12	12	4	2	4	Y	44	44	4	16	1	Y
28-Pin (210-Mil) SSOP	CY8C28452-24PVXI	–40 °C to 85 °C	Y	8	12	4	1	4	N	24	24	4	16	1	Y
28-Pin (210-Mil) SSOP (Tape and Reel)	CY8C28452-24PVXIT	–40 °C to 85 °C	Y	8	12	4	1	4	N	24	24	4	16	1	Y
56-Pin SSOP OCD	CY8C28000-24PVXI	–40 °C to 85 °C	Y	12	12	4	2	4	Y	44	44	4	16	1	Y

Note For Die sales information, contact a local Cypress sales office or Field Applications Engineer (FAE).

1. 10-bit SAR ADC does not meet DNL/INL specification.

■ **Problem Definition**

The 10-bit hardware SAR ADC does not meet datasheet accuracy specifications for DNL and INL under some conditions.

■ **Parameters Affected**

INLSAR10: Integral nonlinearity

DNLSAR10: Differential nonlinearity

■ **Trigger Condition(S)**

The SAR ADC DNL has been measured greater than 2 LSB over temperature in all cases, as compared to the datasheet specification of 1.5 LSB.

When using the VPWR (Vdd) reference configuration, the SAR ADC DNL has been measured over temperature at 2 LSB for a supply voltage of 3.3 V. With a supply voltage of 5.5 V, the DNL has been measured greater than 3.5 LSB.

■ **Scope of Impact**

Inaccurate converted data.

■ **Workaround**

- Use an alternate ADC implementation (DelSig, ADCINC) available in CY8C28xxx devices.
- Avoid CPU operations that change the address and data buses while A-D conversion is running with internal Vpwr (Vdd) as Vref.
- Use un-buffered RefHi as ADC Vref. This may have a negative effect on the analog blocks in the analog array due to the noise introduced on RefHi reference.

■ **Fix Status**

Silicon fix is not planned. The workaround mentioned above should be used.

2. Wrong data read from IDAC_CRx and DACx_D registers.

■ **Problem Definition**

The CPU may read an incorrect value of bits 0, 3, 5, or 7 from the following registers:

- IDAC_CR0
- IDAC_CR1
- DAC0_D
- DAC1_D

■ **Parameters Affected**

F_{CPU1} and F_{CPU2} from the device data sheet.

■ **Trigger Condition(S)**

When CPU Clock is set at its highest frequency setting (24 MHz nominal).

■ **Scope of Impact**

Incorrect data read from affected registers.

■ **Workaround**

Temporarily slow down CPU Clock frequency to 12 MHz nominal (or lower) when affected registers are read.